

PATENT A

## NTHE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	:	Pierre C. Fazan et al.	)	Group Art Unit Unknown
App. No.	:	09/037,945	)	3/A
Filed	:	March 10, 1998	)	516/99 N
For	:	STREAMLINED FIELD ISOLATION PROCESS	)	5/6/99 THEN
Examiner	:	Unknown	,	

## PRELIMINARY AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

Dear Sir:

Prior to examination on the merits of the above-referenced patent application, please amend the application as indicated below.

## **IN THE CLAIMS:**

Please cancel Claims 5-7 and 10.

1. (Amended) A [field isolation] process of forming an integrated circuit, comprising: growing a silicon diexide field isolation region on a semiconductor wafer by means of a hydrogen-free oxidant at a pressure less than about 30 atm; and

forming a gate oxide without a prior sacrificial oxidation.

(Amended) The process of Claim 1, wherein the oxidant [comprises substantially only] consists essentially of oxygen.

3. (Amended) The process of Claim 1, [further comprising] wherein forming the field isolation region comprises exposing the semiconductor [wafer] substrate to the oxidant at an oxidant partial pressure greater than 5 atm.